(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
10 June 2004 (10.06.2004)

PCT

(10) International Publication Number
WO 2004/049424 A2

(51) International Patent Classification[7]: H01L 21/44, 21/48, 21/50, 23/34

(21) International Application Number: PCT/IL2003/001007

(22) International Filing Date: 27 November 2003 (27.11.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/429,352 27 November 2002 (27.11.2002) US

(63) Related by continuation (CON) or continuation-in-part (CIP) to earlier application:
US 09/623,573 (CIP)
Filed on 2 September 2001 (02.09.2001)

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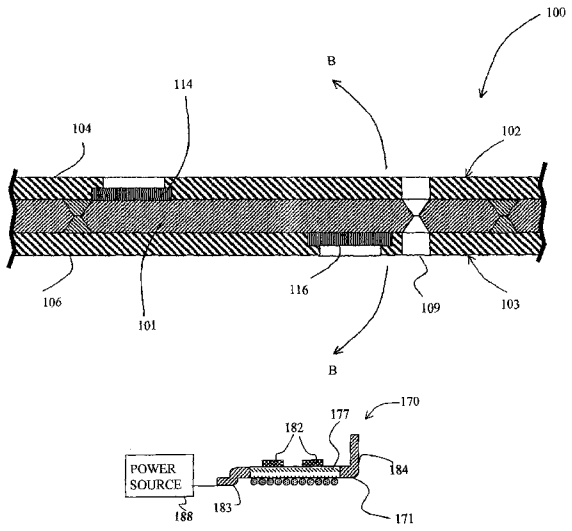
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(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: MICROELECTRONIC PACKAGING AND COMPONENTS



(57) Abstract: The present invention is for substrates for use in interposers for electronic packaging purposes. One preferred embodiment of the present invention is a substrate for use in a Spring Connector Matrix (SCM) interposer having an array of electrically insulated spring connectors each having a fixed end portion and a floating end portion resiliently flexibly coupled to its associated fixed end portion and capable of being independently displaceable in a plane substantially perpendicular to the SCM interposer's major surfaces. Another preferred embodiment of the present invention is a substrate intended to be folded along one or more predetermined fold lines for forming a 3D interposer. Folding is intended at wings which may be wholly formed of valve metal material or may include one or more electrically insulated valve metal traces electrically connected to one or more interconnect regions intended for ICs either single or double sided mounted thereon.

WO 2004/049424 A2

Published:
— *without international search report and to be republished upon receipt of that report*

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